1. (amended)   A silicon wafer having a B-stageable underfill material deposited on one face of the wafer, the B-stageable underfill comprising a combination of two chemical compositions,

a first composition that is a liquid, or a solid dissolved or dispersed in a solvent, and

a second composition that is a solid or semi-solid material at room temperature, dispersible or dissolvable either in the first composition if the first composition is a liquid, or in the solvent for the first composition if the first composition is a solid dissolved or dispersed in a solvent,

the second composition having a curing temperature or curing temperature range higher than the curing temperature or curing temperature range of the first composition,

the having curing temperatures or curing temperature ranges sufficiently separated to allow the composition with the lower curing temperature, the first composition, to cure without curing the composition-with-the-higher-curing-temperature, the second composition,

characterized in that the first composition has been cured and the second composition is uncured.

7. (amended)   A B-stageable underfill composition comprising a combination of two chemical compositions,

a first composition that is a liquid, or a solid dissolved or dispersed in a solvent, and

a second composition that is a solid or semi-solid material at room temperature, dispersible or dissolvable either in the first composition if the first composition is a liquid, or in the solvent for the first composition if the first composition is a solid dissolved or dispersed in a solvent,

the second composition having a curing temperature or curing temperature range higher than the curing temperature or curing temperature range of the first composition,

the ~~having~~ curing temperatures or curing temperature ranges sufficiently separated to allow ~~the composition with the lower curing temperature,~~ the first composition, to cure without curing the ~~composition with the higher curing temperature, the~~ second composition.